

	Type	Hits	Search Text	DBs	Time Stamp
1	IS&R	10118	(257/621,675,685,686,698,699,708,712,713,717,723,735,737,777,778).CCLS.	USPAT	2008/01/22 10:55
2	IS&R	8361	(257/621,675,685,686,698,699,708,712,713,717,723,735,737,777,778).CCLS.	US_PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/01/22 15:35
3	BRS	145	(adhesive bonding) with (epoxy adj resin) same (heat adj (sink radiation radiator))	USPAT	2008/02/04 04:35
4	BRS	158	(adhesive bonding) with (epoxy adj resin) same (heat adj (sink radiation radiator))	FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/02/04 04:36
5	BRS	400	stack\$5 near3 (chip die device) and (adhesive adhesion bond bonding) and (protective passivation) and (heat adj (sink radiation radiator))	USPAT	2008/02/04 04:39
6	BRS	371	stack\$5 near3 (chip die device) and (adhesive adhesion bond bonding) and (protective passivation) and (heat adj (sink radiation radiator))	US_PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/02/04 04:56
7	BRS	9	(stack\$5 near3 (chip die device) and (adhesive adhesion bond bonding) and (protective passivation) and (heat adj (sink radiation radiator)) and (thick thickness)).clm.	US_PGPUB	2008/02/04 05:08
8	BRS	3248	(heat adj (sink radiation radiator)) with (thick thickness)	USPAT	2008/02/04 08:45
9	BRS	1073	(heat adj (sink radiation radiator)) near3 (thick thickness)	USPAT	2008/02/04 08:46
10	BRS	37	(heat adj (sink radiation radiator)) near3 (thick thickness) and (stack\$5 near3 (chip die device))	USPAT	2008/02/04 08:46
11	BRS	53	(heat adj (sink radiation radiator)) near3 (thick thickness) and (stack\$5 near3 (chip die device))	USPAT	2008/02/04 08:47

	Type	Hits	Search Text	DBs	Time Stamp
12	BRS	57	(heat adj (sink radiation radiator)) near3 (thick thickness) and (stack\$5 near3 (chip die device))	US-PGPUB; USOCR; FPRS; EPO; IPO; DERWENT, IBM_TDB	2008/02/04 08:57
13	BRS	8	((heat adj (sink radiation radiator)) and (thick thickness) and (stack\$5 near3 (chip die device)) and (insulating insulation dielectric) and stack\$5).clm.	US-PGPUB	2008/02/04 09:19